

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hung Chih Chen</td> <td>05/10/2005</td> </tr> <tr> <td>Shijian Li</td> <td>05/11/2005</td> </tr> <tr> <td>John M. White</td> <td>05/13/2005</td> </tr> <tr> <td>Ramin Emami</td> <td>07/03/2005</td> </tr> <tr> <td>Fred C. Redeker</td> <td>05/14/2005</td> </tr> <tr> <td>Steven M. Zuniga</td> <td>05/09/2005</td> </tr> <tr> <td>Ramakrishna Cheboli</td> <td>06/15/2005</td> </tr> </tbody> </table>		Name	Execution Date	Hung Chih Chen	05/10/2005	Shijian Li	05/11/2005	John M. White	05/13/2005	Ramin Emami	07/03/2005	Fred C. Redeker	05/14/2005	Steven M. Zuniga	05/09/2005	Ramakrishna Cheboli	06/15/2005
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Ramakrishna Cheboli	06/15/2005																
RECEIVING PARTY DATA																	
Name:	Applied Materials, Inc.																
Street Address:	P. O. Box 450A																
City:	Santa Clara																
State/Country:	CALIFORNIA																
Postal Code:	95052																
PROPERTY NUMBERS Total: 1																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11046189</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11046189												
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CORRESPONDENCE DATA																	
Fax Number:	(408)986-3090																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
Email:	barbara_holt@amat.com																
Correspondent Name:	Applied Materials																
Address Line 1:	P.O. Box 450A																
Address Line 4:	Santa Clara, CALIFORNIA 95052																
NAME OF SUBMITTER:	Barbara Holt																
Total Attachments: 8																	

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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

Hung Chih Chen 2419 Karen Drive #1 Santa Clara, CA 95050
Shijian Li 1202 Donington Drive San Jose, CA 95129
John M. White 2811 Colony View Place Hayward, CA 94541
Ramin Emami 1485 DeRose Way, #124 San Jose, CA 95126

Fred C. Redeker 1801 Sioux Drive Fremont, CA 94539
Steven M. Zuniga 351 Los Robles Road Soquel, CA 95073
Ramakrishna Cheboli 3111 Coronado Drive, M/S 1512 Santa Clara, CA 95050

(hereinafter referred to as Assignors), have invented a certain invention entitled:

Vibration Damping During Chemical Mechanical Polishing

for which application for Letters Patent in the United States was filed on 1/28/2005, under Serial No. 11/046,189, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing

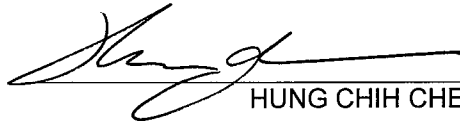
or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

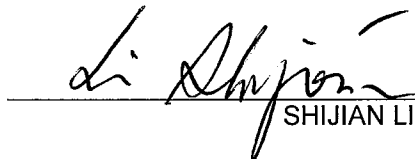
4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

Date: May 10, 2005


HUNG CHIH CHEN

Date: May 11, 2005


SHIJIAN LI

Date: 5/13/05


JOHN M. WHITE

Date: _____

RAMIN EMAMI

Date: _____

FRED C. REDEKER

Date: 5/9/05


STEVEN M. ZUNIGA

Date: _____

RAMAKRISHNA CHEBOLI

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Date:

07/03/2005



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STEVEN M. ZUNIGA

Date:

15th June '05



RAMAKRISHNA CHEBOLI

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